

## Day 1 - Monday 17th April 2023

18:30 Pre-conference networking drinks reception sponsored by EPIC

## Day 2 - Tuesday 18th April 2023

08:00 Registration and welcome refreshments

08:50 Housekeeping by Michael Lebby and David Cheskis, Conference Chairs

### Hybrid PICs - Sponsored by Vanguard Automation

09:00 **Heterogeneous photonic integration of InP on silicon**

*Presented by Martijn Heck - Eindhoven University of Technology*

09:15 **Advancements of 3D printed opto-mechanical structures for optical coupling using Two-Photon Polymerization**

*Presented by Jörg Smolenski - Nanoscribe*

09:30 **Tricks to mix PICs: How to realize hybrid Photonic IC design**

*Presented by Ronald Broeke - Bright Photonics*

09:45 **Enabling next Generation Photonic Integration and Packaging Solutions with Photonic Wire Bonding (PWB) and 3D-Printed Micro-Lenses**

*Presented by Sebastian Skacel - Vanguard Automation*

10:00 **Hybrid integration and fiber-pigtailing for 3 μm SOI PICs**

*Presented by Timo Aalto - VTT*

10:15 Morning Break

10:45 **High-volume scalability in cavity enhanced MEMS-PIC inertial sensors**

*Presented by Lia Li - Zero Point Motion (in collaboration with Cornerstone)*

11:00 **Photonic IC Modules Outside the Telecom Window**

*Presented by Arne Leinse - LioniX International*

### Chip-scale packaging

11:15 **Micro-optics for PICs with Advanced Optomechanical Features**

*Presented by Wilfried Noell - SUSS MicroOptics SA*

11:30 **Scaling 3D laser lithography-based packaging of hybrid multi-chip assemblies from prototyping to volume production**

*Presented by Thorsten Mayer - Vanguard Automation*

11:45 **Novel fiber array alignment with core-based positioning control**

*Presented by Simone Cardarelli - MicroAlign*

12:00 **High yield & throughput in optical assembly by self-adaptive production**

*Presented by Colin Dankwart - ficonTEC*

12:15 Lunch Break

### PIC Vision: Revolution and evolution - Sponsored by OPTICA

13:30 **Technology & industrial leadership in PICs for Europe: Collective approach**

*Presented by Dr. Nilufar Bulut - PhotonDelta*

13:45 **Accelerating the path to integrated photonics-based quantum computers via EPDA**

*Presented by Ahsan Alam - Ansys*

14:00 **Energy-efficient integrated photonics for next-generation computing**

*Presented by Thomas Van Vaerenbergh - Hewlett Packard Enterprise*

14:15 **Photonic neuromorphic computing, prospects and requirements**

*Presented by Bert Offrein - IBM*

14:30 **Next generation communication chips made from Pockels-enhanced PICs**

*Presented by Stefan Abel - Lumiphase*

14:45 Afternoon Break

15:15 **Quantum Dot Lasers on Silicon for Highly Parallel Data Transmission**

*Presented by Michael Davenport - Quintessent*

15:30 **Quantum computing, a strategic technology enabled by photonics**

*Presented by Amin Abbasi - imec*

15:45 **Plasmonic PICs: Believe in Your Silicon Photonics Platform But Never Stop Improving**

*Presented by Claudia Hössbacher - Polariton Technologies AG*

### Optimising PICs for optical wireless opportunities

16:00 **Producing an integrated silicon photonics transceiver for 100Gbit/s transmission over 20km**

*Presented by Peter De Dobbelaere - Cisco*

16:15 **The Needs of Automotive and LiDAR for PICs**

*Presented by Bill Ring - Voyant Photonics*

16:30 **Photonic integrated circuits for solid-state LiDAR**

*Presented by Marcus Dahlem - imec*

16:45 Closing Remarks

16:50 Networking Drinks / Dinner Reception

## Day 3 - Wednesday 19th April 2023

08:00 Registration and welcome refreshments

08:50 Housekeeping by Michael Lebbby and David Cheskis, Conference Chairs

### Scaling PICs in volume using foundries

09:00 **Perspectives on silicon photonics foundry: a new era**

*Presented by Anthony Yu - GlobalFoundries*

09:15 **Low loss PICs: From fast prototyping to high volumes**

*Presented by Michael Geiselmann - LIGENTEC*

09:30 **Positioning electro-optic polymer modulators as an optical engine to extend data rate and low power performance for optical networking**

*Presented by Michael Lebbby - Lightwave Logic Inc*

09:45 **Doing More with Less as a Photonics Manufacturing Strategy**

*Presented by Scott Jordan - Physik Instrumente*

10:00 **Flexibility and shorter changeover times in packaging**

*Presented by Niels Jansen - Etteplan*

10:15 **Integrated Photonic Packaging from prototype to production scale up**

*Presented by Jeroen Duis - PHIX*

10:30 Morning Break

11:00 **Accelerating time-to-market through functional verification of PICs**

*Presented by Martin Fiers - Luceda Photonics*

11:15 **Nanoimprint Lithography (NIL) – How to apply for PIC manufacturing and packaging?**

*Presented by Bernd Dielacher - EV Group*

11:30 **Application-specific PIC design – Acceleration and adaptation to custom processes**

*Presented by Andrzej Po?aty?ski - VPIphotonics*

11:45 **Silicon Photonics Process Technologies Considerations for High Volume and Flexibility**

*Presented by Bowen Wang - Tower Semiconductor*

12:00 **Supporting Si Photonics versatility through application specific PDKs**

*Presented by Franck Ernult - Advanced Micro Foundry*

12:15 **Faster Development and Higher Production Output by Smart PIC Assembly and Test Automation**

*Presented by Kurt Hensen - Averno*

12:30 **State-of-the-art and future of Hybrid Silicon Photonic Foundries**

*GlobalFoundries, Tower Semiconductor, and VTT*

13:00 Lunch Break

### Driving deployment in established markets

14:00 **PIC testing optimization as a crucial step for PIC technology deployment**

*Presented by Daria Lavrova - Keysight Technologies*

14:15 **Integrated Photonics in Precision Farming**

*Presented by Carol de Vries - PhotonDelta*

14:30 **Design of 3D heterogenous chips and systems for optical datacom and I/O**

*Presented by Twan Korthorst - Synopsys*

14:45 **Can PICs fit into access networks?**

*Presented by Francisco Rodrigues - PICadvanced*

15:00 Afternoon Break

15:30 **Advancements in Optical Engines Based on Monolithically Integrated InP Photonic Chips**

*Presented by Mehrdad Ziari - Infinera*

15:45 **Accelerating high-speed electro-optical interconnects utilizing Silicon-organic electro-optic modulators**

*Presented by Adrian Mertens - SilOrix*

16:00 **Optical Interconnects for Advanced Packaging Glass Substrates**

*Presented by Andreas Matiss - Corning*

16:15 **Market and technologies trends for PICs**

*Presented by Eric Mounier - Yole Group*

16:30 Closing Remarks

